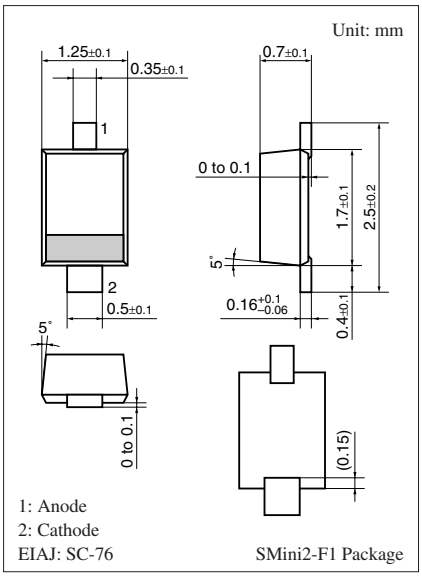
MA2J114 (MA114)

Silicon epitaxial planar type

For small power rectification



Marking Symbol: 1E

■ Features

- S-mini type package, allowing high-density mounting
- High reverse voltage V_R

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	150	V
Maximum peak reverse voltage	V_{RM}	150	V
Output current	I_O	200	mA
Repetitive peak forward current	I_{FRM}	600	mA
Non-repetitive peak forward surge current *	I_{FSM}	1	A
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

Note) *: t = 1 s

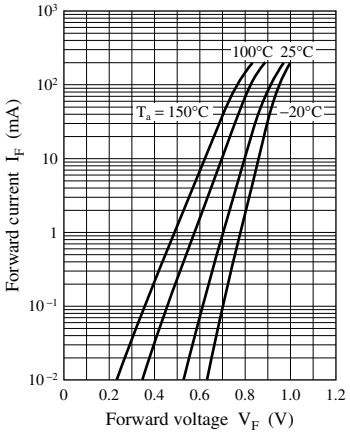
■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	I_F = 200 mA			1.2	V
Reverse current	I_R	V_R = 150 V			200	nA
Terminal capacitance	C_t	V_R = 0 V, f = 1 MHz		4.5		pF

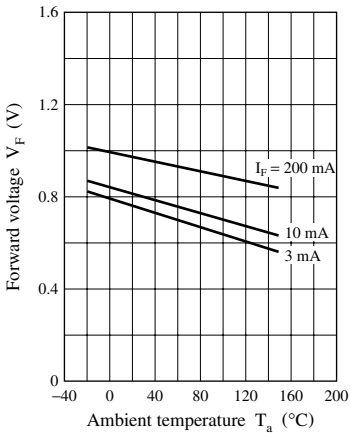
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. Absolute frequency of input and output is 3 MHz.

Note) The part number in the parenthesis shows conventional part number.

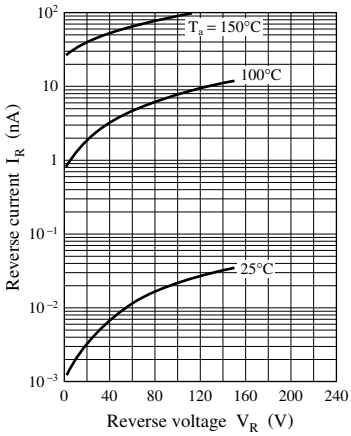
I_F — V_F



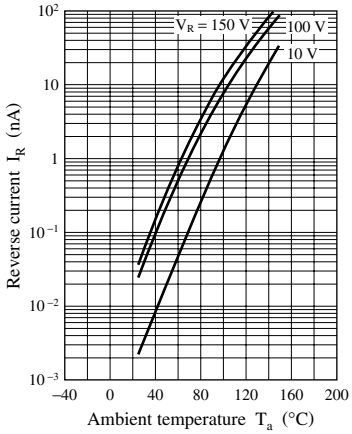
V_F — T_a



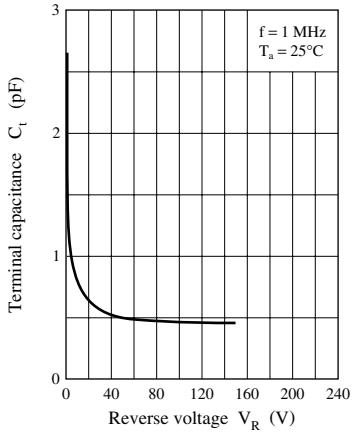
I_R — V_R



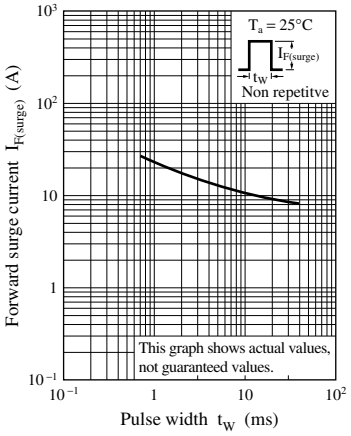
I_R — T_a



C_t — V_R



$I_{F(surge)}$ — t_W



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